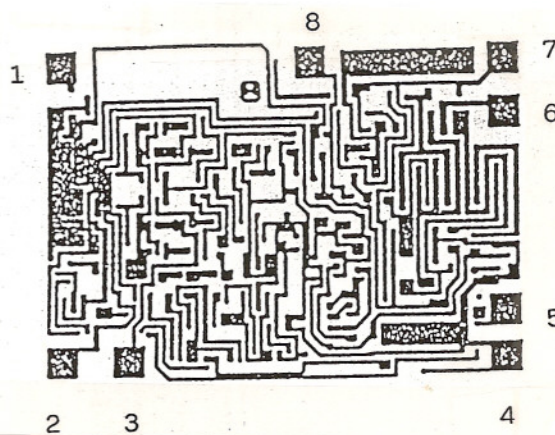




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>PAD NO</u>	<u>FUNCTIONS</u>
1	BALANCE
2	-IN
3	+IN
4	-V
5	BALANCE
6	OUT
7	+V
8	COMP

Note: Substrate must be unbiased.

Topside Metal: Al
Backside: Si
Backside Potential:
Mask Ref:
Bond Pads : .004" Min

APPROVED BY: CB
MFG: Harris



DIE SIZE : .073" x .052"
THICKNESS: .019"

DATE: 1/25/01
P/N: HA-2625-2

DG 10.1.2
 Rev A 3-4-99